MITSUBISHI ELECTRIC

**< HVIGBT MODULES >**

# CM750HG-130R

**HIGH POWER SWITCHING USE**
**INSULATED TYPE**

4th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

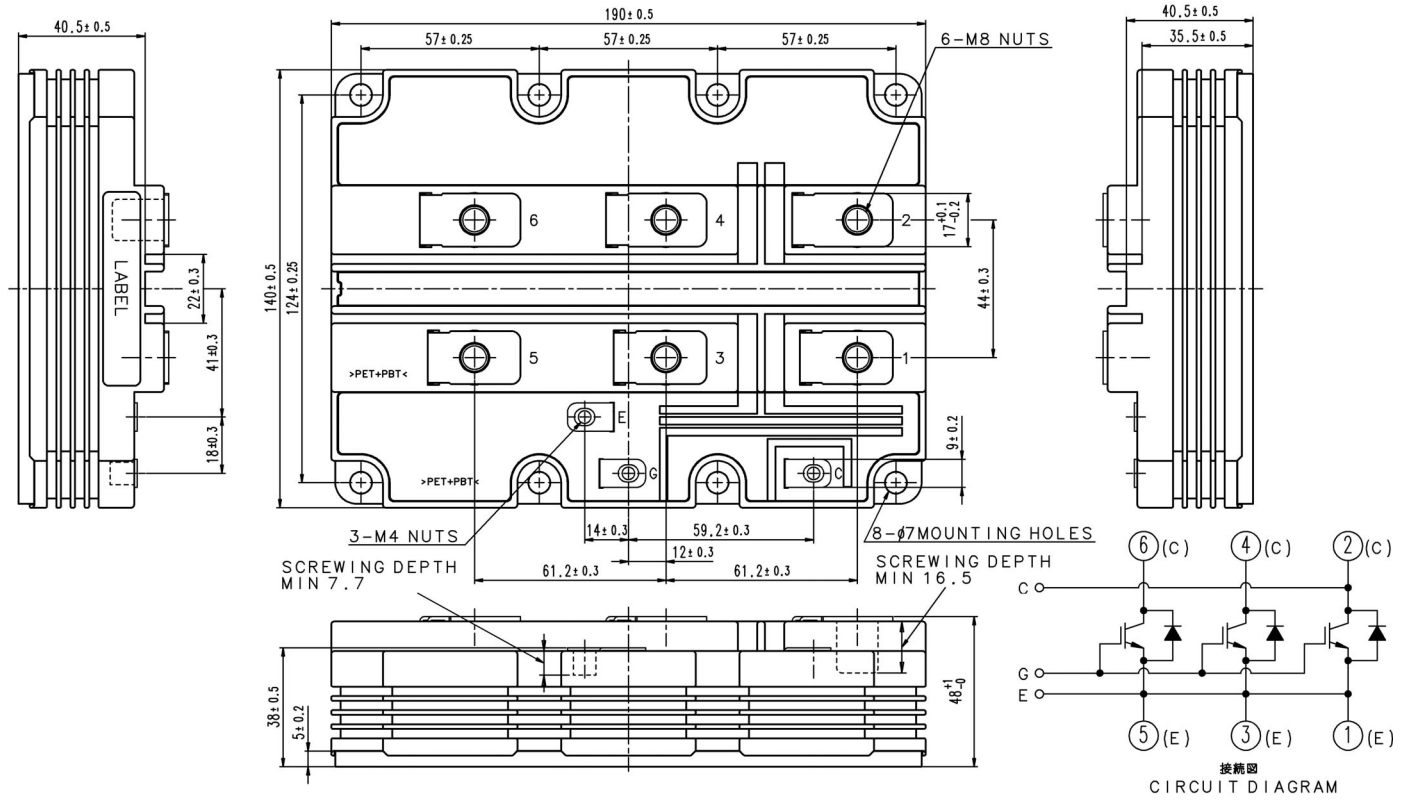
**CM750HG-130R**

- $I_C$ ..... 750A
- $V_{CES}$ ..... 6500V
- 1-element in a pack
- High Insulated type
- LPT-IGBT / Soft Recovery Diode
- AlSiC baseplate

## APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

**OUTLINE DRAWING & CIRCUIT DIAGRAM** **Dimensions in mm**



## MAXIMUM RATINGS

| Symbol | Item | Conditions | Ratings | Unit |
|---|---|---|---|---|
| $V_{CES}$ | Collector-emitter voltage | $V_{GE}$ = 0V, $T_j$ = +125°C | 6500 | V |
| | | $V_{GE}$ = 0V, $T_j$ = +25°C | 6300 | |
| | | $V_{GE}$ = 0V, $T_j$ = −50°C | 5700 | |
| $V_{GES}$ | Gate-emitter voltage | $V_{CE}$ = 0V, $T_j$ = 25°C | ± 20 | V |
| $I_C$ | Collector current | DC, $T_c$ = 95°C | 750 | A |
| $I_{CRM}$ | | Pulse (Note 1) | 1500 | A |
| $I_E$ | Emitter current (Note 2) | DC | 750 | A |
| $I_{ERM}$ | | Pulse (Note 1) | 1500 | A |
| $P_{tot}$ | Maximum power dissipation (Note 3) | $T_c$ = 25°C, IGBT part | 10400 | W |
| $V_{iso}$ | Isolation voltage | RMS, sinusoidal, f = 60Hz, t = 1 min. | 10200 | V |
| $V_e$ | Partial discharge extinction voltage | RMS, sinusoidal, f = 60Hz, $Q_{PD}$ ≤ 10 pC | 5100 | V |
| $T_j$ | Junction temperature | | −50 ~ +150 | °C |
| $T_{jop}$ | Operating junction temperature | | −50 ~ +125 | °C |
| $T_{stg}$ | Storage temperature | | −55 ~ +125 | °C |
| $t_{psc}$ | Short circuit pulse width | $V_{CC}$ = 4500V, $V_{CE}$ ≤ $V_{CES}$, $V_{GE}$ =15V, $T_j$ =125°C | 10 | μs |

## ELECTRICAL CHARACTERISTICS

| Symbol | Item | Conditions | | Limits | | | Unit |
|---|---|---|---|---|---|---|---|
| | | | | Min | Typ | Max | |
| $I_{CES}$ | Collector cutoff current | $V_{CE}$ = $V_{CES}$, $V_{GE}$ = 0V | $T_j$ = 25°C | — | — | 24.0 | mA |
| | | | $T_j$ = 125°C | — | 24.0 | — | |
| $V_{GE(th)}$ | Gate-emitter threshold voltage | $V_{CE}$ = 10 V, $I_C$ =75 mA, $T_j$ = 25°C | | 5.8 | 6.3 | 6.8 | V |
| $I_{GES}$ | Gate leakage current | $V_{GE}$ = $V_{GES}$, $V_{CE}$ = 0V, $T_j$ = 25°C | | −0.5 | — | 0.5 | μA |
| $C_{ies}$ | Input capacitance | $V_{CE}$ = 10 V, $V_{GE}$ = 0 V, f = 100 kHz<br>$T_j$ = 25°C | | — | 136.0 | — | nF |
| $C_{oes}$ | Output capacitance | | | — | 8.6 | — | nF |
| $C_{res}$ | Reverse transfer capacitance | | | — | 4.0 | — | nF |
| $Q_G$ | Total gate charge | $V_{CC}$ = 3600V, $I_C$ = 750A, $V_{GE}$ = ±15V | | — | 10.5 | — | μC |
| $V_{CEsat}$ | Collector-emitter saturation voltage | $I_C$ =750 A (Note 4)<br>$V_{GE}$ = 15 V | $T_j$ = 25°C | — | 3.80 | — | V |
| | | | $T_j$ = 125°C | — | 4.80 | 5.60 | |
| $t_{d(on)}$ | Turn-on delay time | $V_{CC}$ = 3600 V<br>$I_C$ = 750 A<br>$V_{GE}$ = ±15 V<br>$R_{G(on)}$ = 3.3 Ω<br>$L_s$ = 150 nH<br>Inductive load | $T_j$ = 25°C | — | 1.05 | — | μs |
| | | | $T_j$ = 125°C | — | 1.00 | 1.80 | |
| $t_r$ | Turn-on rise time | | $T_j$ = 25°C | — | 0.18 | — | μs |
| | | | $T_j$ = 125°C | — | 0.20 | 0.50 | |
| $E_{on(10\%)}$ | Turn-on switching energy (Note 5) | | $T_j$ = 25°C | — | 3.35 | — | J |
| | | | $T_j$ = 125°C | — | 4.10 | — | |
| $E_{on}$ | Turn-on switching energy (Note 6) | | $T_j$ = 25°C | — | 3.50 | — | J |
| | | | $T_j$ = 125°C | — | 4.40 | — | |
| $t_{d(off)}$ | Turn-off delay time | $V_{CC}$ = 3600 V<br>$I_C$ = 750 A<br>$V_{GE}$ = ±15 V<br>$R_{G(off)}$ = 33 Ω<br>$L_s$ = 150 nH<br>Inductive load | $T_j$ = 25°C | — | 7.60 | — | μs |
| | | | $T_j$ = 125°C | — | 8.00 | 9.20 | |
| $t_f$ | Turn-off fall time | | $T_j$ = 25°C | — | 0.40 | — | μs |
| | | | $T_j$ = 125°C | — | 0.45 | 1.00 | |
| $E_{off(10\%)}$ | Turn-off switching energy (Note 5) | | $T_j$ = 25°C | — | 3.10 | — | J |
| | | | $T_j$ = 125°C | — | 4.60 | — | |
| $E_{off}$ | Turn-off switching energy (Note 6) | | $T_j$ = 25°C | — | 3.40 | — | J |
| | | | $T_j$ = 125°C | — | 4.90 | — | |

**ELECTRICAL CHARACTERISTICS (continuation)**

| Symbol | Item | Conditions | | Limits | | | Unit |
|---|---|---|---|---|---|---|---|
| | | | | Min | Typ | Max | |
| $V_{EC}$ | Emitter-collector voltage (Note 2) | $I_E$ = 750 A (Note 4), $V_{GE}$ = 0 V | $T_j$ = 25°C | — | 3.30 | — | V |
| | | | $T_j$ = 125°C | — | 3.40 | 4.20 | |
| $t_{rr}$ | Reverse recovery time (Note 2) | $V_{CC}$ = 3600 V, $I_C$ = 750 A, $V_{GE}$ = ±15 V, $R_{G(on)}$ = 3.3 Ω, $L_s$ = 150 nH, Inductive load | $T_j$ = 25°C | — | 0.65 | — | μs |
| | | | $T_j$ = 125°C | — | 0.70 | — | |
| $I_{rr}$ | Reverse recovery current (Note 2) | | $T_j$ = 25°C | — | 800 | — | A |
| | | | $T_j$ = 125°C | — | 900 | — | |
| $Q_{rr}$ | Reverse recovery charge (Note 2) | | $T_j$ = 25°C | — | 630 | — | μC |
| | | | $T_j$ = 125°C | — | 900 | — | |
| $E_{rec(10\%)}$ | Reverse recovery energy (Note 2) (Note 5) | | $T_j$ = 25°C | — | 0.90 | — | J |
| | | | $T_j$ = 125°C | — | 1.70 | — | |
| $E_{rec}$ | Reverse recovery energy (Note 2) (Note 6) | | $T_j$ = 25°C | — | 1.00 | — | J |
| | | | $T_j$ = 125°C | — | 1.80 | — | |

**THERMAL CHARACTERISTICS**

| Symbol | Item | Conditions | Limits | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min | Typ | Max | |
| $R_{th(j-c)Q}$ | Thermal resistance | Junction to Case, IGBT part | — | — | 12.0 | K/kW |
| $R_{th(j-c)D}$ | | Junction to Case, FWDi part | — | — | 22.0 | K/kW |
| $R_{th(c-s)}$ | Contact thermal resistance | Case to heat sink, $\lambda_{grease}$ = 1W/m·k, $D_{(c-s)}$ = 100μm | — | 6.0 | — | K/kW |

**MECHANICAL CHARACTERISTICS**

| Symbol | Item | Conditions | Limits | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min | Typ | Max | |
| $M_t$ | Mounting torque | M8 : Main terminals screw | 7.0 | — | 22.0 | N·m |
| $M_s$ | | M6 : Mounting screw | 3.0 | — | 6.0 | N·m |
| $M_t$ | | M4 : Auxiliary terminals screw | 1.0 | — | 3.0 | N·m |
| m | Mass | | — | 1.4 | — | kg |
| CTI | Comparative tracking index | | 600 | — | — | — |
| $d_a$ | Clearance | | 26.0 | — | — | mm |
| $d_s$ | Creepage distance | | 56.0 | — | — | mm |
| $L_{P\ CE}$ | Parasitic stray inductance | | — | 15.0 | — | nH |
| $R_{CC'+EE'}$ | Internal lead resistance | $T_C$ = 25°C | — | 0.18 | — | mΩ |
| $r_g$ | Internal gate resistance | $T_C$ = 25°C | — | 2.6 | — | Ω |

Note1. Pulse width and repetition rate should be such that junction temperature ($T_j$) does not exceed $T_{jopmax}$ rating.

2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode ($FWD_i$).

3. Junction temperature ($T_j$) should not exceed $T_{jmax}$ rating (150°C).

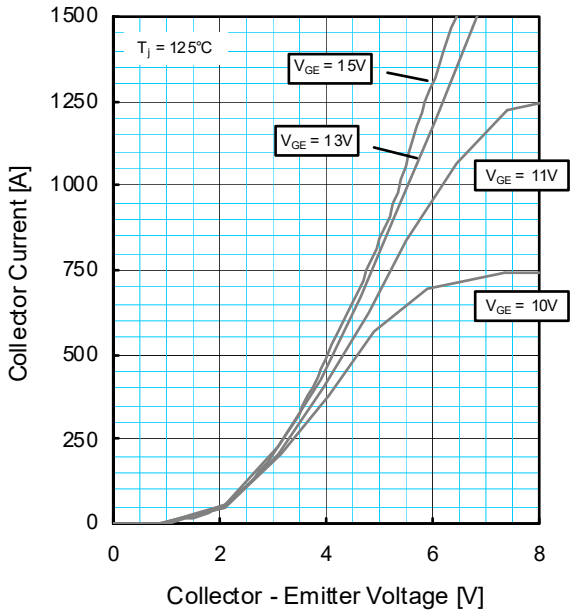
4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

5. $E_{on(10\%)}$ / $E_{off(10\%)}$ / $E_{rec(10\%)}$ are the integral of $0.1V_{CE} \times 0.1I_C\ dt$.

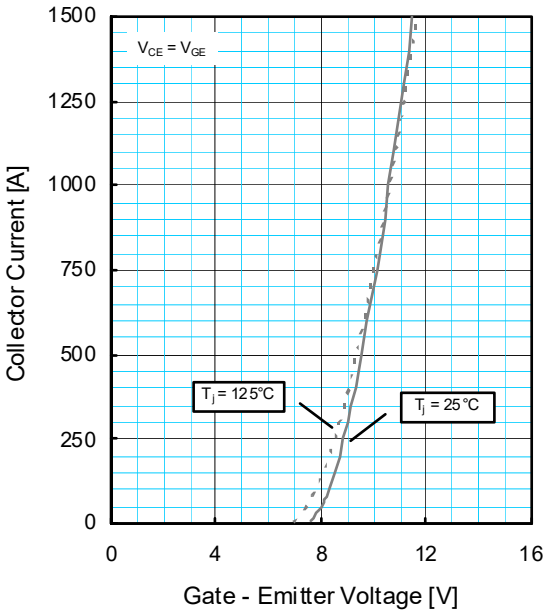
6. Definition of all items is according to IEC 60747, unless otherwise specified.

## PERFORMANCE CURVES

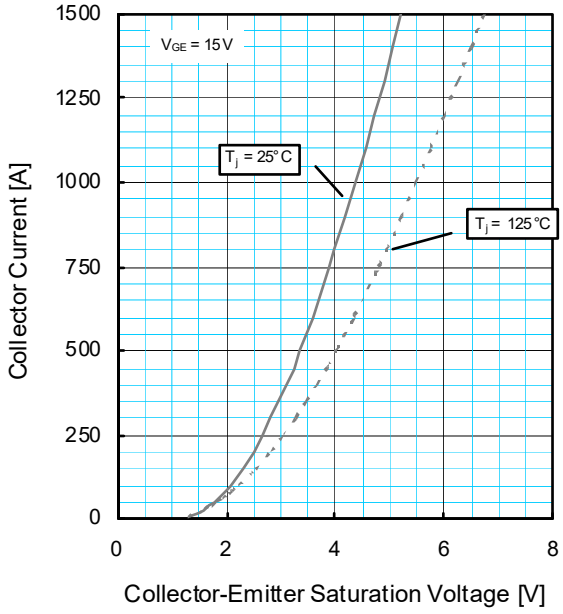
### OUTPUT CHARACTERISTICS (TYPICAL)



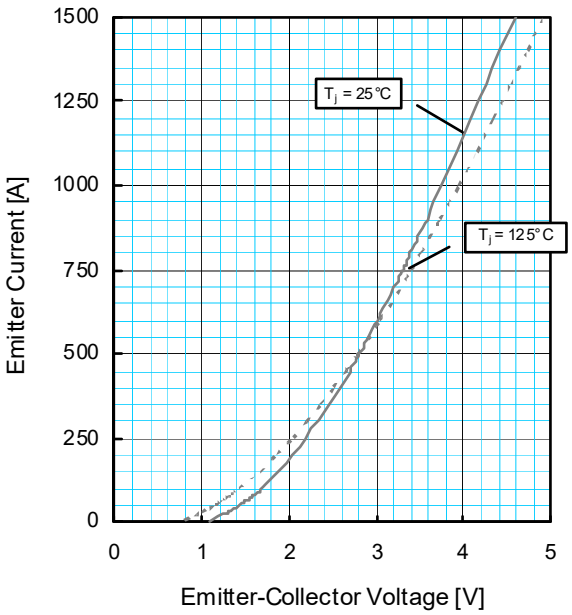

### TRANSFER CHARACTERISTICS (TYPICAL)




### COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)

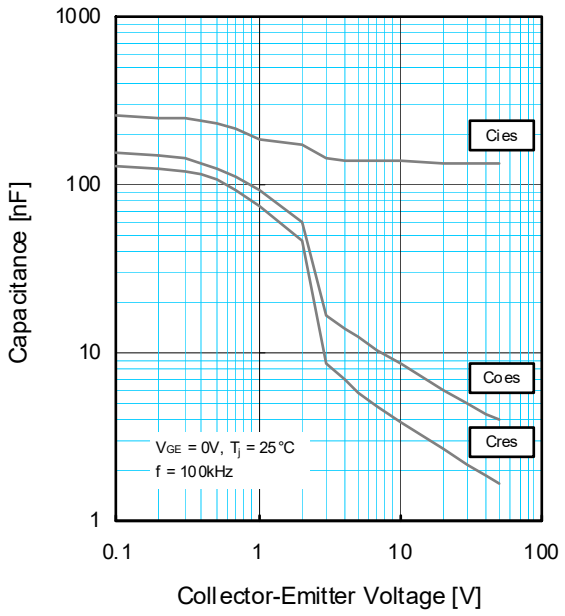



### FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)

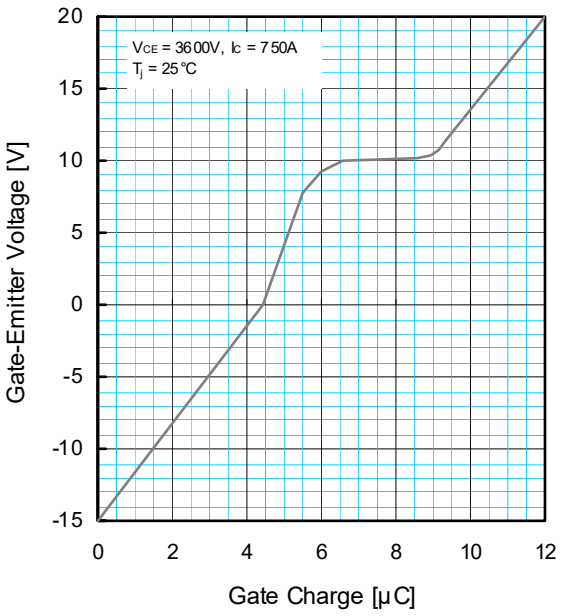


## PERFORMANCE CURVES

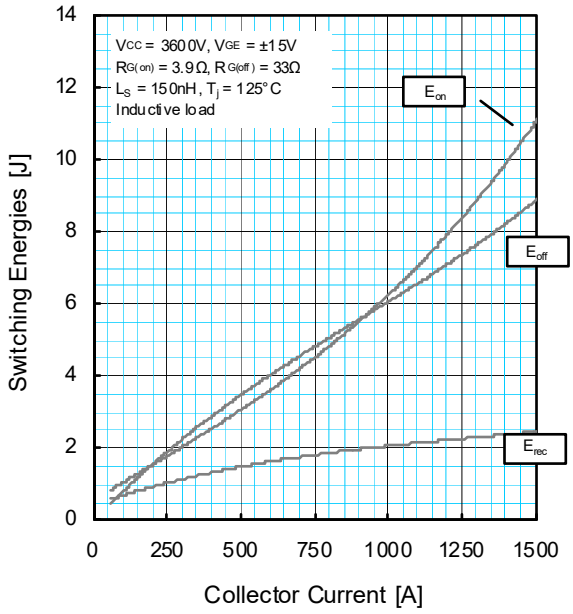
### CAPACITANCE CHARACTERISTICS (TYPICAL)



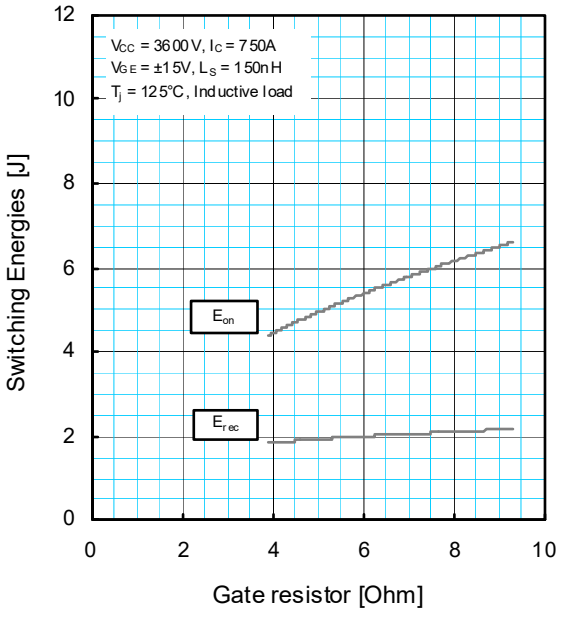

### GATE CHARGE CHARACTERISTICS (TYPICAL)




### HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

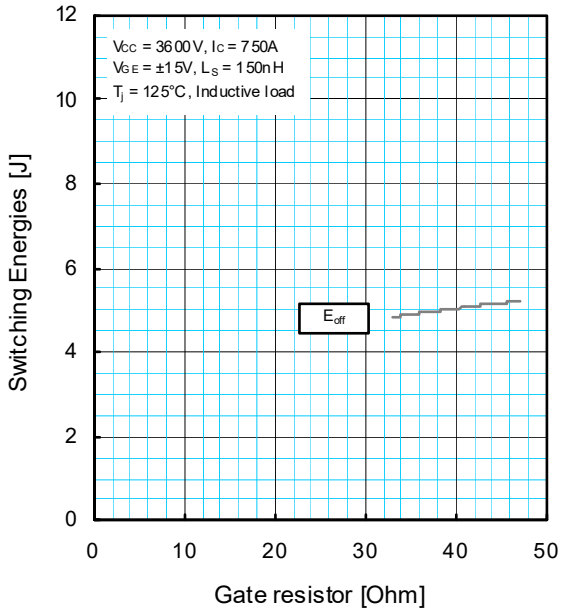



### HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

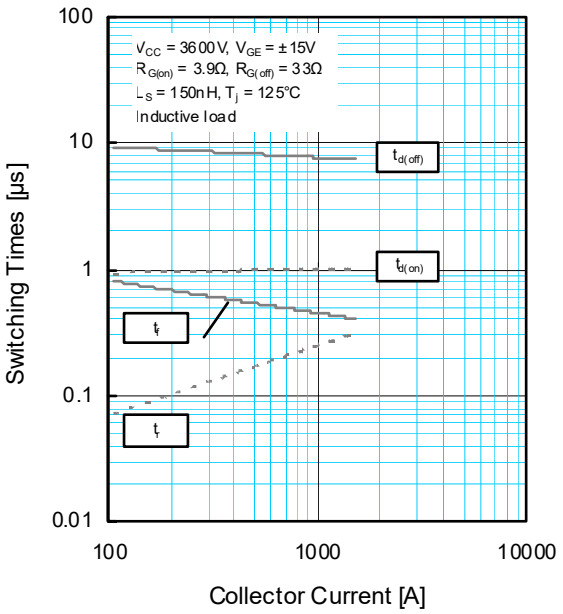


## PERFORMANCE CURVES

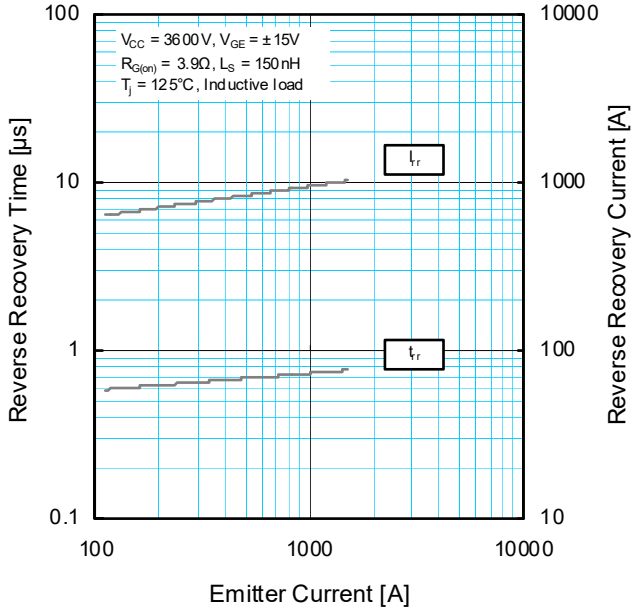
### SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



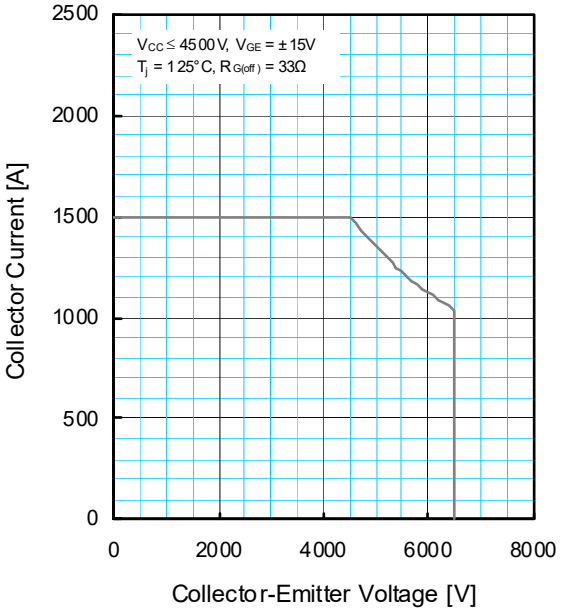

### HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)HALF-BRIDGE




### FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)

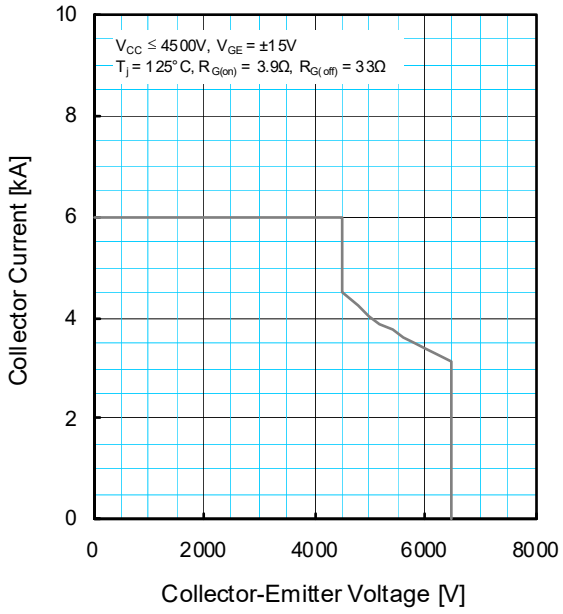



### REVERSE BIAS SAFE OPERATING AREA (RBSOA)

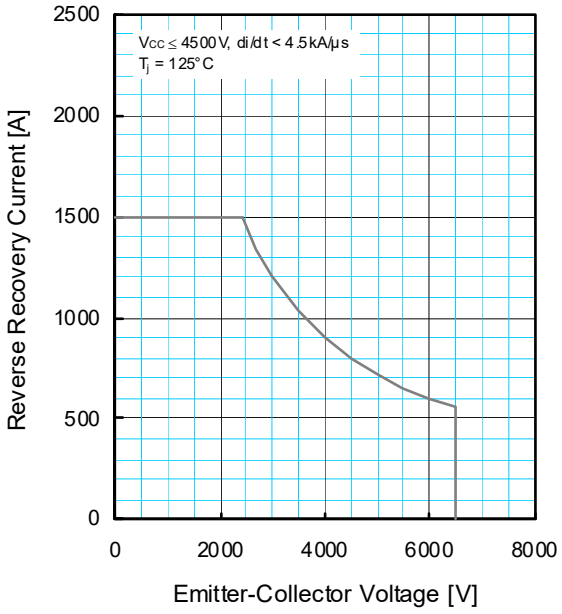


## PERFORMANCE CURVES

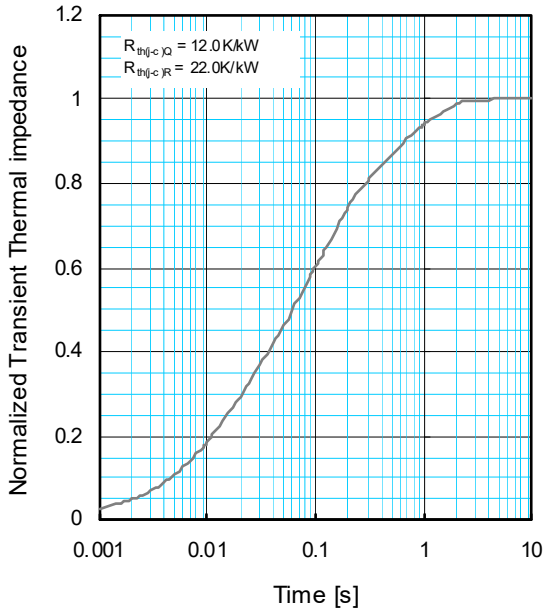
### SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)




### FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)




### TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS




$$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_i \left\{ 1 - exp\left( -\frac{t}{\tau_i} \right) \right\}$$

| | 1 | 2 | 3 | 4 |
|---|---|---|---|---|
| $R_i$ [K/kW] : | 0.0055 | 0.2360 | 0.4680 | 0.2905 |
| $t_i$ [sec] : | 0.0001 | 0.0131 | 0.0878 | 0.6247 |

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